REMARKS/ARGUMENTS

This Amendment is supplemental to the Amendment filed 8 July 2004 in response to the Official Action dated 14 April 2004, and responsive to the Notice of Non-Compliant Amendment mailed 16 July 2004. Corrected AMENDMENTS TO THE SPECIFICATION and AMENDMENTS TO THE CLAIMS sections are hereby submitted. The remarks originally submitted are repeated herein.

Responsive to the objection of the specification and drawing, Applicant has amended the title, abstract and FIG. 5A in response to the detailed action.

Reconsideration of the application is respectfully requested for the following reasons:

Rejection of Claims 26-50 Under 35 U.S.C. §112, second paragraph

In response to the rejections of claims 26, 35, 36 and 37, Applicant has amended claims 26, 35, 36 and 37 according to the specification originally filed without involving any issue of new matter. Reconsideration of claims 26, 35, 36 and 37 is respectfully requested.

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Rejection of Claims 26, 33-37 and 40-42 Under 35 U.S.C. §102(b)

Claims 26, 33-37 and 40-42 are rejected under 35 U.S.C. §102 (b) as being anticipated by Applicant's disclosure. In the rejected claims, only Claim 26 is independent.

Examiner states that the conventional cleaning method of the background of the claimed invention uses the steps as claimed with the exception of the immersion time, a first time, second time, second immersion time, and third time which means the times as claimed in claim 26 is inherent in the conventional method disclosed at pages 2 and 3 and in Fig. 3.

However, in the background of the claimed invention, several drawbacks of the conventional method are also pointed out. As shown in FIG. 2 of the claimed invention, after the clean steps are completed, metal corrosion would occur on the sidewalls of the metal lines 102. There is a large quantity of recesses occurring on the sidewalls of the metal lines 102, which look like mouse bites. The metal corrosion does not influence the device yield, but reduces reliability of the devices. Moreover, the defect count of the wafer on KLA map is very large, which shields other defects related to the device yield. As a result, the other defects can be not found out at on-line monitoring.

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The mechanism of removing polymer residues on the sidewalls of the metal lines with the stripping solution is the stripping solution attacks aluminum or its oxide to remove polymer residues from the sidewalls of the aluminum metal lines, and then dissolving the removed polymer residues in the stripping solution. When there is excess water in the stripping solution Metal corrosion would occur on the sidewalls of the metal lines 102, as shown in FIG. 2. FIG. 4 is a diagram of aluminum etching rate versus water content of the stripping solution when using the stripping solution containing alcohol amine, dihydroxylbenzene, water, hydroxylamine and anticorrosion agent to clean aluminum alloy. As shown in FIG. 4, when water content is below 60 wt.%, aluminum etching rate is smaller than 0.1 Å/min, while water content is up to 98 wt.%, aluminum etching rate is up to 58 It is apparent that a little of the stripping solution in a large quantity of Therefore, the water would result in serious metal corrosion on aluminum alloy. stripping solution left on the wafer needs to be completely removed before immersing the wafer in the overflow bath 322 so as to avoid metal corrosion occurring on the sidewalls of the metal lines 102 formed on the wafer.

Accordingly, the claimed invention provides an improved clean method to overcome the drawbacks of the prior art. As to the immersion time, a first time, second time, second immersion time, and third time in the claim actually can provide unexpected results and is not inherent in the conventional method disclosed at pages 2 and 3 and in Fig. 3 because the time the wafer is maintained

without contacting the stripping solution after being removed from the stripping solution is for dripping down the stripping solution left on the wafer. Generally, a conventional clean method would not specifically remove the stripping solution remained on the wafer taking from the stripping solution before immersing in a large quantity of water in view of production cost and the remaining stripping solution in a large quantity of water would result in scrious metal corrosion on Applicant emphasizes that sidewall of metal lines such as aluminum alloy lines. the times as claimed in claim 26 is not inherent in the conventional method since the additional time for placing the wafer over the stripping solution without contacting the stripping solution is to drip down the stripping solution left on the wafer before immersing into water to prevent serious metal corrosion on sidewall of metal lines. For example, the wafer would not be particularly maintained without contacting the first organic solvent bath after being removed from the first organic solvent bath and before being immersed into the second organic solvent bath in the conventional method in order to increase production capability and to prevent the residual chemical mark. In the conventional method, the wafer is always immediately immersed into the second organic solvent bath after being removed from the first organic solvent bath in less than 10 seconds so that the stripping solution remained on the wafer would be also immersed into the overflow bath to cause serious metal corrosion of metal lines.

Thus the times as claimed in claim 26 to drip down the stripping solution left on the wafer can produce unexpected results contrary to the conventional method.

Rejection of Claims 26, 33-36 Under 35 U.S.C. §102(a)

Claims 26, 33-36 are rejected under 35 U.S.C. §102 (a) as being anticipated by Lee (U.S. 6,276,372) . In the rejected claims, only Claim 26 is independent.

Examiner uses the same reason which states that the times as claimed in claim 26 is inherent in the method disclosed by Lee. Lee actually discloses a process for removing photoresist residue or other polymeric material from a substrate with a specific cleaning composition as described in the detailed action. The method of Lee actually discloses a method almost the same with any other conventional method except the specific cleaning composition. The times as claimed in claim 26 actually is not inherent in the method of Lee either since the additional time for maintaining the wafer without contacting the stripping solution is to drip down the stripping solution left on the wafer before immersing into water

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to prevent serious metal corrosion on sidewall of metal lines. Lee dose not
disclose this particular limitation which can produce unexpected results or prevent
serious metal corrosion on sidewall of metal lines.

Rejections of Claims 27-32 and 37-50 Under 35 U.S.C. §103(a)

Claims 43-50 are rejected under 35 U.S.C. §103 (a) as being unpatentable over Applicant's disclosure in combination with Torek (US 6,562,726 or US 6,453,914).

Although Torek discloses introducing agitating gas into a rinse bath but Torek dose not teach introducing agitating gas into a clean method of the claimed invention which Applicant's disclosure fails to disclose either.

Claims 27-32 and 37-50 are rejected under 35 U.S.C. §103 (a) as being unpatentable over Lee in combination with Torek (US 6,453,914).

The reason of the obviousness rejection based on the combination of Lee and Torck is actually the same with the rejection based on the combination of

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Applicant's disclosure and Torck. Applicant respectfully disagrees with
Examiner's opinion which states that it is obvious for one skilled in the art to
repeat the rinsing step, to adjust the stripping time and the rinsing time to obtain
optimum result since the limitation in the claimed invention can produce
unexpected result. Although the stripping time and the rinsing time are
determined based on particular material being removed, but the time of
maintaining the wafer without contacting the stripping solution is determined
based on the stripping solution left on the wafer before immersing into water in the
claimed invention.

Conclusion

In light of the above remarks to the claims, Applicant contends that claimed invention is patentable thereover. Claims 26-50 are now in condition for favorable consideration and allowance of Claims 26-50 are most respectfully requested.

This Amendment was prepared by Applicant, and is being submitted without substantive change by the undersigned Attorney.

Respectfully submitted,

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Dated: 30 July 2004

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CERTIFICATE OF FACSIMILE TRANSMISSION

I hereby certify that this paper is being facsimile transmitted to the U.S. Patent and Trademark Office, Art Unit #1746, at (703) 872-9306, on the date shown below.

For: ROSENBERG, KLEIN & LEE

DAVID I. KLEIN

7/30/04 Date

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is considered non-compliant because it has failed to meet the requirements of The amendment document filed on 37 CFR. 1.121, as amended on June 30, 2003 (see 68 Fed. Reg. 38611, Jun. 30, 2003). In order for the amendment document to be compliant, conection of the following item(s) is required. Only the corrected section of the non-compliant amendment document must be resubmitted (in its entirety), e.g., the entire "Amendments to the claims" section of applicant's amendment document must be re-submitted. 37 CFR 1.121(h). THE FOLLOWING CHECKED (X) ITEM(S) CAUSE THE AMENDMENT DOCUMENT TO BE NON-COMPLIANT: 1. Amendments to the specification: A. Amended paragraph(s) do not include markings. B. New paragraph(s) should not be underlined. П C. Other 2. Abstract: Amendments to the drawings: Amendments to the claims: A. A complete listing of all of the claims is not present B. The listing of claims does not include the text of all claims (including withdrawn claims) 口 C. Each claim has not been provided with the proper status identifier, and as such, the individual status of each claim cannot be identified. D. The claims of this amendment paper have not been presented in ascending numerical order. \Box E. Other:

For further explanation of the amendment format required by 37 CFR 1.121, see MPEP Sec. 714 and the USPTO website at <a href="http://www.uspto.gov/web/offices/pac/dapp/opla/preognotice/offices/pac/dapp/opla/pac/dapp/op

If the non-compliant amendment is a PRELIMINARY AMENDMENT, applicant is given ONE MONTH from the mail date this letter to supply the corrected section which complies with 37 CFR 1.121. Failure to comply with 37 CFR 1.121 will result non-entry of the preliminary amendment and examination on the merits will commence without consideration of the propochanges in the preliminary amendment(s). This notice is not an action under 35 U.S.C. 132, and this ONE MONTH time like not extendable.

If the non-compliant amendment is a reply to a NON-FINAL OFFICE ACTION (including a submission for an RCE), since the amendment appears to be a bona fide attempt to be a reply (37 CFR 1.135(c)), applicant is given a TIME PERIOD ONE MONTH from the mailing of this notice within which to re-submit the corrected section which complies with 37 CFR 1. in order to avoid abandonment. EXTENSIONS OF THIS TIME PERIOD ARE AVAILABLE UNDER 37 CFR 1.136(2).

If the amendment is a reply to a FINAL REJECTION, this form may be an attachment to an Advisory Action. The period response to a final rejection continues to run from the date set in the final rejection, and is not affected by the non-comparatus of the approximent.

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